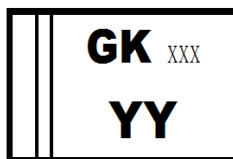


FEATURES

- * For surface mount application
- * Built-in strain relief
- * Excellent clamping capability
- * Low profile package
- * Fast response time: Typically less than 1.0ps from 0 volt to BV min.
- * Typical I_R less than 1 A above 10V
- * High temperature soldering guaranteed: 260°C / 10 seconds at terminals

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: Color band denotes cathode end except Bidirectional
- * Mounting position: Any



- "GK" represents the brand name
- "XXX" represents the periodic code
- "YY" represents the product type marking

VOLTAGE RANGE

180 Volts

600 Watts Peak Power

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

RATINGS	SYMBOL	VALUE	UNITS
Peak Power Dissipation at $T_A=25^\circ\text{C}$, $T_P=1\text{ms}$ (NOTE 1)	P_{PK}	Minimum 600	Watts
Peak Forward Surge Current at 8.3ms Single Half Sine-Wave superimposed on rated load (JEDEC method) (NOTE 3)	I_{FSM}	100	Amps
Typical Thermal Resistance Between junction and case	$R_{\theta J-C}$	20	$^\circ\text{C/W}$
Typical Thermal Resistance Between junction and Air	$R_{\theta J-A}$	95	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

NOTES:

1. Non-repetitive current pulse per Fig. 3 and derated above $T_A=25^\circ\text{C}$ per Fig. 2.
2. Mounted on Copper Pad area of 5.0mm^2 (.013mm Thick) to each terminal.
3. 8.3ms single half sine-wave, duty cycle = 4 pulses per minute maximum.

DEVICES FOR BIDIRECTIONAL APPLICATIONS

- 1. For bi-directional use C suffix for Types .
- 2. Electrical characteristics apply in both directions.

RATING AND CHARACTERISTIC CURVES

FIG.1-PEAK PULSE POWER DERATING CURVE

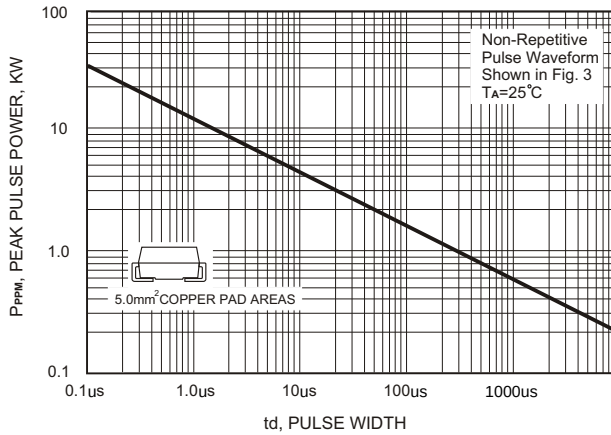


FIG.2-PULSE DERATING CURVE

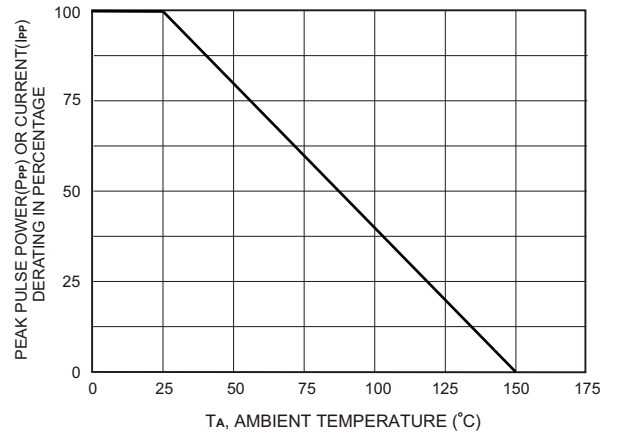


FIG.3-PULSE WAVE FORM

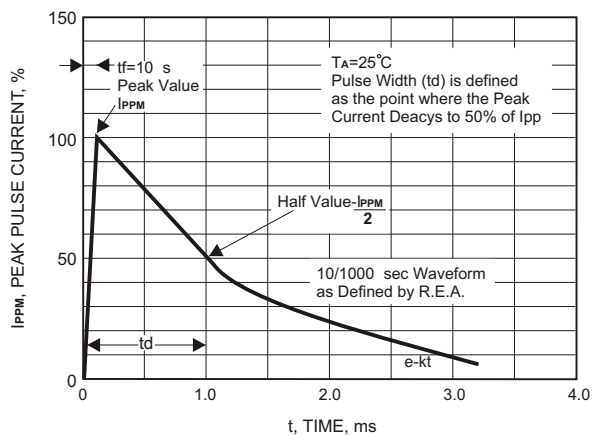


FIG.4 MAXIMUM NON REPETITIVE PEAK FORWARD SURGE CURRENT

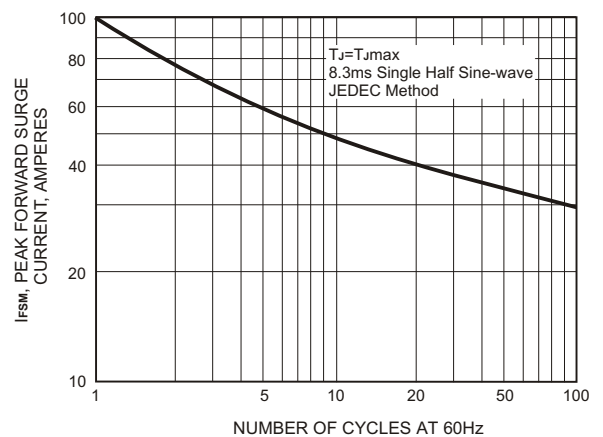
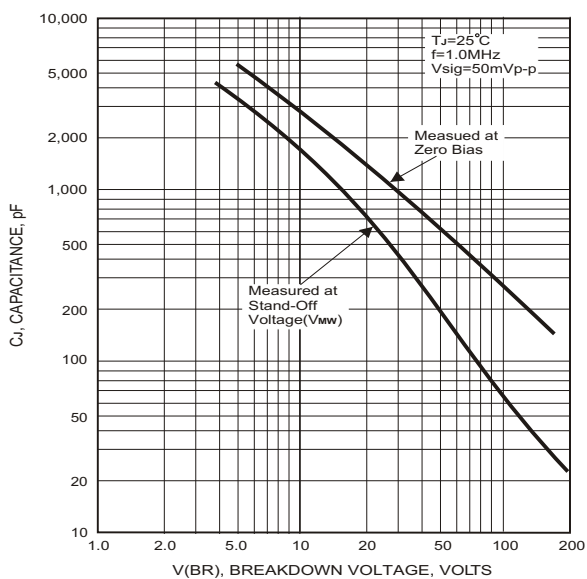


FIG.5-TYPICAL JUNCTION CAPACITANCE

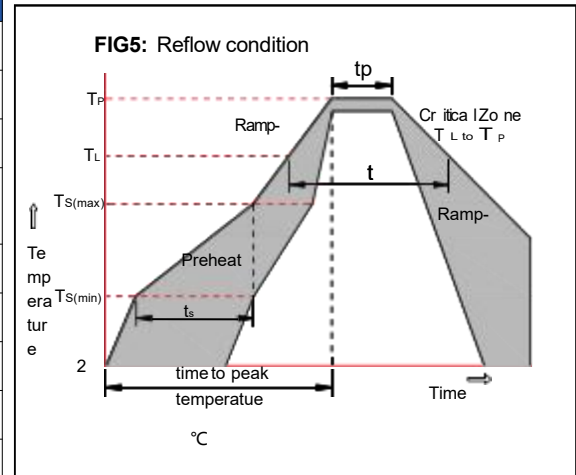


Characteristics at Ta = 25°C

Type		Reverse Stand-off Voltage	Breakdown Voltage $V_{BR} @ I_T$		Test Current I_T	Maximum Reverse Leakage	Max. Clamp Voltage $V_C @ I_{PP}$	Peak Pulse Current I_{PP}
UNI	BI	V_{RMW} V	Min V	Max V	mA	μA	V	A
SMBJ180A	SMBJ180CA	180	201	222	1	1	292	2.1

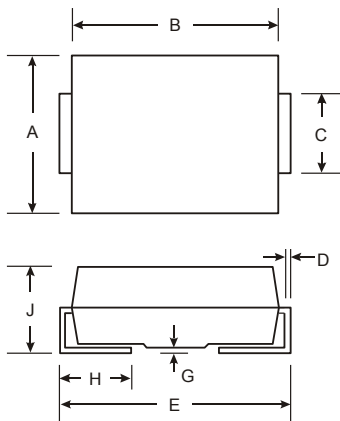
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

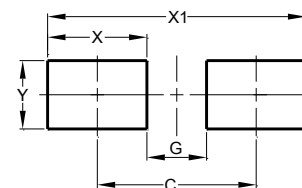


Package Dimensions & Suggested Pad Layout

SMB

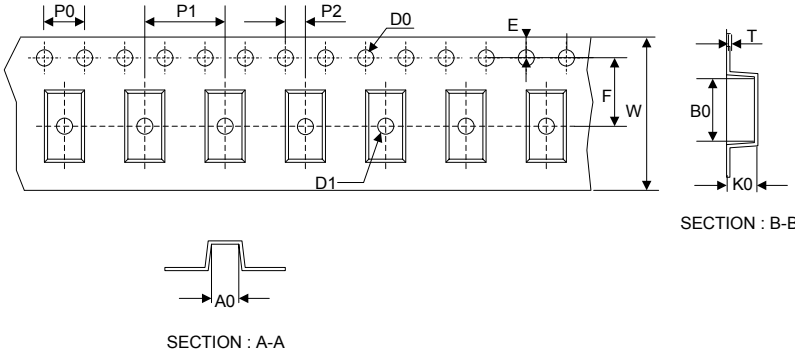
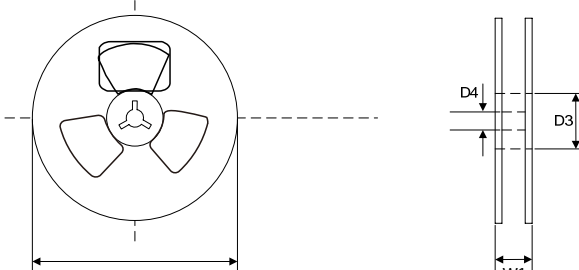


SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.11
D	0.15	0.31
E	5.08	5.59
G		0.20
H	0.76	1.50
J	2.13	2.44
All Dimensions in mm		



Dimensions	Value (in mm)
C	4.70
G	2.20
X	2.50
X1	7.20
Y	2.80

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.20
		D1	1.60±0.20
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	4.00±0.20
		B0	5.45±0.20
		K0	2.50±0.25
		T	0.20±0.10
		D2	330.0±5.0
		D3	73.0Min.
13" Reel		D4	14.0±2.5
		W1	16.0±2.5
		Quantity: 3000PCS	